



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20190520000.0
Datasheet for MSP430F5172, MSP430F5152, MSP430F5132
MSP430F5171, MSP430F5151, MSP430F5131
Information Only

Date: May 21, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
MSP430F5172IDAR	null
MSP430F5172IRSBT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190520000.0	PCN Date:	May 21, 2019
Title:	Datasheet for MSP430F5172, MSP430F5152, MSP430F5132, MSP430F5171, MSP430F5151, MSP430F5131		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



MSP430F5172, MSP430F5152, MSP430F5132
MSP430F5171, MSP430F5151, MSP430F5131

SLAS619Q – AUGUST 2010 – REVISED JULY 2018

Changes from May 10, 2016 to July 19, 2018

Page

• Changed entry for Body Size of DSBGA package in <i>Device Information</i> table	2
• Updated Section 3.1, Related Products	7
• Removed D and E dimension lines from the YFF pinout (for the package dimensions, see the <i>Mechanical Data</i> in Section 8).....	10
• Updated the note that begins "If DVIO is not supplied by the same source as DVCC..." on Section 5.3, Recommended Operating Conditions	14
• Updated notes (1) and (2) and added note (3) in Section 5.32, Wake-up Times From Low-Power Modes and Reset	34
• Removed ADC10DIV from the formula for the TYP value in the second row of the $t_{CONVERT}$ parameter in Section 5.39, 10-Bit ADC, Timing Parameters , because ADC10CLK is after division	40
• Changed the MAX value of the t_{EN_CMP} parameter with Test Conditions of "CBPWMD = 10" from 1.5 μ s to 100 μ s in Section 5.43, Comparator_B	43
• Corrected typo in TDHCLKTRIM maximum value (changed from 128 to 127) in Test Conditions in Section 5.45, Timer_D, Local Clock Generator Frequency	45
• Corrected the port and pin numbers for the "Data transmit" row in Table 6-5, BSL Functions	54



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SLAS619R – AUGUST 2010 – REVISED SEPTEMBER 2018

Changes from July 20, 2018 to September 20, 2018

Page

• Added typical conditions statements at the beginning of Section 5, Specifications	14
• Updated Section 7.4, Documentation Support	101

The datasheet number will be changing.

Device Family	Change From:	Change To:
MSP430F5172, MSP430F5152, MSP430F5132 MSP430F5171, MSP430F5151, MSP430F5131	SLAS619P	SLAS619R

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/MSP430F5131>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

MSP430F5131IDA	MSP430F5131IDAR	MSP430F5131IRSBR	MSP430F5131IRSBT
MSP430F5131IYFFR	MSP430F5131IYFFT	MSP430F5132IDA	MSP430F5132IDAR
MSP430F5132IRSBR	MSP430F5132IRSBT	MSP430F5132IYFFR	MSP430F5132IYFFT
MSP430F5151IDA	MSP430F5151IDAR	MSP430F5151IRSBR	MSP430F5151IRSBT
MSP430F5151IYFFR	MSP430F5151IYFFT	MSP430F5152IDA	MSP430F5152IDAR
MSP430F5152IRSBR	MSP430F5152IRSBT	MSP430F5152IYFFR	MSP430F5152IYFFT
MSP430F5171IDA	MSP430F5171IDAR	MSP430F5171IRSBR	MSP430F5171IRSBT
MSP430F5171IYFFR	MSP430F5171IYFFT	MSP430F5172IDA	MSP430F5172IDAR
MSP430F5172IRSBR	MSP430F5172IRSBT	MSP430F5172IYFFR	MSP430F5172IYFFT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com